

Title (en)  
Electroplating process

Title (de)  
Verfahren zum galvanischen Aufbringen einer Oberflächenbeschichtung

Title (fr)  
Procédé d'électrodéposition

Publication  
**EP 0565070 B1 19970730 (DE)**

Application  
**EP 93105726 A 19930407**

Priority  
DE 4211881 A 19920409

Abstract (en)  
[origin: US5415761A] A process for electrochemically depositing a structured surface layer on a component, such as a machine component, particularly a steel water cylinder of a printing press, is disclosed. The process comprises the steps of defining an electrical parameter, such as a potential and/or an electrical current, effecting an electro-chemical layer deposition; and depositing a surface layer on the component with a structured outer surface topography. The depositing step is performed by providing an initial pulse of the electrical parameter and forming a plurality of island formations of deposition material on a surface of the component to be electro-chemically coated, and subsequently providing a follow-up pulse of the electrical parameter and causing a growth of the deposition material on the plurality of islands for causing the structured outer surface topography.

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**C25D 5/18**

IPC 8 full level  
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CPC (source: EP US)  
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Cited by  
EP4012074A1; EP3000918A1; CN111201340A; US11136685B2; US11732373B2; EP3438330A1; WO2019025203A1

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